

Risks Swift

Risk Assessment - Initial Version			1 low 2 medium 3 high	1 low 2 medium 3 high		Measures of Risk Assessment				
Group	Risk	Root Cause / Consequence	Impact	Probability	Factor	Measure	Owner	Date	Result	Status
SW LCM4 / PT1	SW Platform Risks Reduced Droptest performance / breaking of soldering connections in droptest	see SW Platform Risks reduced pcb thickness 0,87 in combination with leadfree soldering.	3 3	3 2	9 6	Measures see SW Platform measures create fallbacksolution (underfilling) 03.05 unterfilling only limited possible with current PCB (not an option anymore) 03.05 RCC foil will be added on PCB Material (is implemented) 08.05: drop tests with B1 22.09: drop tests with B1+ 8.12.: see drop tests on Dec. 15-20th. 08.02.: B2 drop test still failing according to our requirements; results are discussed in meeting Feb 9th. 05.04.06 droptest for B2 passed	SW Platform Schroeter, Anzinger- Bitsch	ongoing S0-HW tested A1 S45 tested B1+ 20.12.06 09.02.2006		
LCM1	Gluing of 12 key is not good enough Risk of removal of keypad by environmental influence	not enough surface for glue	3	2	6	8.12.: Tested in B1+: 6,98N und 9,33N Further climatical tests will be done B1+ 31.03: DOE is planned for today (31.03.) Afterwards a verification run will be done. Silitec glue was improved. 05.04.06 Keypad DOE has been done on 03.04.06; results need to be discussed	Schröter/ Faust/ Anzinger Bitsch	S25HW ew8 M April		
MD	changes regarding ground contact not tested.	We can get problems with drop test, cycle test and the slider function	3	2	6	8.2.: Countermeasures were applied at KHVartec and will be available with Pilot/ RU.		B2 Pilot	B2: ground contact SLC was bended and crack by drop test 31.03.: ground contact was implemented and works fine; lubrication will be inserted by Perlos.	
BB	delivery problems for Battery (ramp up)	Battery is single source	3	1	3	- keep close contact to Sanyo - Management must report clear and reliable statements (no "games") - Audit at Sanyo 5.12.05 no trouble up to now with Sanyo, so no delivery problem expected 31.03.: in order to cope with out quantity requirements Sanyo needs to invest in a second tooling.	Bach/Liebener w	B1+ 10.02.2006 M April 06	actually no problem of Sanyo, more of R&D (what security system must be implemented) 7.3.06 1st phase: with PTC, 30V-Fet 2nd phase: with breaker, 30V-Fet 3rd phase: with breaker, 20V-Fet done	
LCM4 / PT1	Assembly of Keypad cannot be qualified	No material for a proper automatic process available until now.	3	1	3	Track quality of keypads on tape and reel 8.2.: Silitech ok, DK-UIL showed problem in automatic gluing. In disussion with MD and DK-UIL. Samples will be shipped cw7 (t.b.c.). DOE has been done; results need to be discussed (MD / QM-HW / PT)	Schroeter	Pilot		
LCM4 / PT1	new SD card reader cannot be handled in production test.	late running change on SD card reader	3	2	6	Investigation ongoing. 10.02.: test adapter for new SD card reader will be available 05.04.06 testrun with SD-Card Reader planned for 06.04.06	Schroeter	cw15		
LCM4 / PT1	Logistical problem with handling phones in repair loop with old and new SD card reader (follow risk from new SD card reader)	late running change on SD card reader	3	1	3	Investigation ongoing. 05.04.06 Line needs to be empty of parts; adapters needs to be changed	Schroeter	cw15		
QM HW	temperature spec not met	metallic design's conductivity is high.	3	1	3	measurements are ongoing 08.02.: B1+ tests showed that we meet 45 degrees and hardly 50 degrees. Must be re-checked with B2.		09.12.2005 cw14 (interim results cw10)	okay now with reduced temperature range EN60950 still missing to be done	
SD QM	broken flexes in Perlos deliveries	flexes can move in trays	3	1	3	Holder for flex foreseen, Perlos is in the loop. 8.2.: Trays & Spacer adapted;	Hessel/ Berchtenbreiter	B2 pilot	New Trays and Spacers have been made	

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BB	Sanyo Battery: no safety tests available	Battery will possibly not fulfill Siemens requirements in safety	2	1	2	Safety tests in early state of development, test of several setups (Thermofuse/PTC) -> first Test results available E11/05 (improved cells) according to Sanyo no safety problem (in written form?) 5.12.05 Sanyo tests improved cells with breaker (instead of Thermofuse), passed tests in Erlangen will be done with B2-Samples in Jan/06 7.2.06 Tests of battery with breaker postponed due to ongoing discussions	Bachl (Liebenow)	E11/05 04/06 13.02.2006	7.3.06 overcharge tests with PTC and 30V-Fet done in Erlangen, tests passed. Tests with Breaker and 20V-Fet must be done as soon as available.	
ST1	Related to SW Multimedia solution I expect to get high trouble to stabilize the SW at all.	Architecture w/o ATI chipset	2	1	2	minimum timeline between S25 and DS has to be assured to get SW stable 31.03.: risk remains with streaming and fast track; optimization ongoing.	85er platform	M4-timeline- commitment S25 DS	not seen as high risk today.	
GP	Project does not reach Target BOM		2	3	6	Close monitoring of BOM 31.03.: intensive discussion done for S25; we saw that the original BOM targets were not achieved but this was communicated to management and was therefore accepted with S25 declaration.	Dunzel	ongoing S25-BOM new S3 BOM	Mozart as a single source is communicated and agreed by SP (Jörg Dunzel)	
BB	not enough Epson displays will be available.	Display controller shortages	3	2	6	SP and BB are in contact with Epson to get a clear understanding / commitment from Epson 31.03.: Phillips confirmed us that they could handle 100% delivery (but this is not our preferred solution)	Bachl, Dunzel	10.02.2006 ongoing	share for Philips is increased to 70%, Epson actually 30% (beginning from June) CR for qualification of Epson-Display with Nec-Controller is raised.	
BB	Problems with again adapted Phillips displays.	Phillips display will be adapted to increase yield.	2	1	2	Test new version in environmental test. (again with Unimicon PCBs built) 31.03.: last tests with new Polarizer will be done until April 12th.	Bachl	M/E Feb 2006 12.04.2006	7.3.06 test samples with new Polarizer available, environmental tests running	
BB	Not enough Sibley Flashes for planned pilot and ramp up. 2nd source ST is not ready in time.	Intel reduced their delivery forecasts. Qualification and SW CR was set up immediately after this notice but might take too long and/or show SW performance problems.	2	3	6	- HW qualification is ongoing - SW CR is under evaluation - SP is in negotiation with Intel /ST	Bachl Hien Dunzel	28.02.2006 ongoing	7.3.06 qualification of ST-Flash is running 31.03.: drop tests are showing currently problems (ongoing)	
MD	Keypad get lost after aging	Environmental tests showed big differences in the pulling forces even w/o aging.	2	3	6	Investigations are ongoing: - gluing machine pressure - glue Special care in Unimicon built + results after aging still outstanding. 10.04.: see DOE (April3rd) and according verification run (cw15)	Berchtenbreiter/ Anzinger-Bitsch (for results)	E-cwZ cw17		
QM-HW	SD / SIM card reader breaks in drop and/or has connection. Problem in 30cm drop (Kipp-Fall-Test) with SIM card reader.	Soldering of SD/ SIM card reader is not okay.	3	2	6	PT1 is working on that problem 05.04.06 soldering tests in cw14 by PT1	Schröter	cw7		
MD	metal cover does not stick to phone	Problems with falling metal cover seen in B2.	3	1	3	Painting is masked in the gluing area. Will be applied for pilot run.	Berchtenbreiter	Pilot	must be checked with drop tests in pilot.	
SW	power consumption above M1 commitments	SW optimization in terms of power saving are not sufficient for reaching our M1 requirements	3	1	3	Optimizations are ongoing 29.03.: Talk and StandBy values are ok; Streaming figures can only be measured after a complete SW implementation	Hien	AS S3 step2		
SW	HW Performance not sufficient for FastTrack (valid for both STM and Intel flashes)	Fast Track is very performance consuming but not yet completely implemented	3	1	3	Implementation and optimization is ongoing; HW cannot be changed anymore	Hien	S3 step2		
SW	CQ status is not sufficient for DS	bug fixing rate is too low and/or big bugs are only detected late	2	2	4	we are currently on track	Hien	DS		
ST	SW not S3 mature on March 31st.	still lots of exits	2	3	6	see today's telco for S3 maturity	SW/ST	S3		
ST2	we do not pass reliable SIM test cases (TA relevant)	cross talk effects of illumination to SIM signals	3	3	9	type approval test case passed; the risk is what happens at the operators (if they do re-tests)	HW	DS		
GP	KHVatec reduces quantities	KHVatec	3	3	9	SD QM is pushing	SD QM/ Dunzel	ongoing		

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MD	sweat test not passed	different materials show bad results in sweat tests	2	3	6	It is not yet clear what the impact is. New Kestrel surfaces did not show significant improvements.	Berchtenbreiter	ongoing, running change in series	
SW QM	ASP parameters are not available for S3	late check in of SW V121	2	3	6	S3 could be declared with restrictions.	Schreiner	S3	
SW QM	SW stability not mature for DS	SW development process	2	3	6	SW optimization / stabilization is ongoing	Hien/ Jäger	DS	
SD QM	Overlaps or process problems at Perlos	Overlapping Metal Cover.	3	2	6	Changes to Slider Upper case (short term: Perlos re-work ongoing)	Berchtenbreiter/ Barlau	S3	
SD QM	Vibra will Damage the Flex / Virba does not run	The Vibra Motor can contact the Flex when turning	3	1	3	Ensure that the Vibra can not contact the Flex Identify where this Problem comes from => Flex re-desing (shortening) will be initiated.	Anzinger Bitsch/ Berchtenbreiter	S3	

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Risk Analysis												
last update 25-Apr-06 updates in blue; grey line = risk has become obsolete			<div><div>There is a Problem</div><div>There is a Problem</div><div>Might become a Problem</div><div>Might become a Problem</div><div>No Problem</div><div>No Problem</div></div>									
ID	Major	Likelihood	Description	Actions	Update	Responsible	Back Fall solution	Risk Status	Follow-up Date	Business Impact	Impact Status	Status
1	EA	0%	EL Driver and EL foil cause interferences with GSM receiver -> bad RX performance while backlight is on -> LEDs will be used for keypad illumination	sensitivity tests as soon as HW and SW functionality is available	No EL-Foil!	Stefan S.	4 Layer MMI, partly shielding of EL driver, schematic changes.	⊖		Low Market Acceptance; Cost Increase; Time Delay	⊖	
2	EA	0%	ESD problems caused by influence of metallic frontcover and ungrounded metallic keypad caps. Mobile is switching off at 6kV on the keypad (navkey). Not Important for approval but for quality, less for end user. 15 kV required by Q.	ESD tests with metallic parts on Phone samples. Earliest possible with B1 phones depending on Mechanics and SW. Counter measure : additional metal pins for ESI guiding. Check with SW for batterie measurement algorithm	schematic changes implemented in B1+. Retesting with B1+. Changes in B1+ MMI PCB has also be investigated	Stefan S.	a) 4 Layer MMI PCB GND b) shielding of display flex	⊖	1/ Okt 05	Low Market Acceptance; Cost Increase; Time Delay due to failed approval	⊖	
3	EA	0%	Antenna performance too bad because of metal front cover (depending on possible ground connector positions)	Verify Antenna Performance with M0 parts. Looks promising based on M0 measurements.	Unclear status of Uppercase regarding diecast frame could badly influence the antenna performance and could cause a time delay.	Oelschlaeger/ Frank S.	design modifications/ adaptations	⊖	1/ Okt 05	Low Market Acceptance; Cost Increase; Time Delay	⊖	
4	EA	0%	SAR value above 1.0W/kg (1g) because of Metal front cover	Investigations with metal front cover necessary. Prepare potential contact areas at Front Cover. Looks promising based on M0 measurements.		Oelschlaeger	weaken SAR requirements	⊖	1/ Okt 05	Low Market Acceptance; Cost Increase; Time Delay	⊖	
5	EA	0%	ESD Problem with Display	ESD tests with first displays as soon as they available	retesting with B1+	Stefan S.	enlarge distance between Display module and front cover, use glass not plastic as display window	⊖	1/ Okt 05	Low Market Acceptance; Cost Increase; Time Delay	⊖	
6	EA	0%	higher harmonics of GSM carriers caused by HITACHI PA (known problem), propagated by metallic front cover	Find Blocking Measure	schematic changes implemented in B1+. Retesting with B1+ 2x900 Harmonics due to layout change in Battery	Stefan S.		⊖	16/ Dez 05	TTM delay	⊖	
7	EA	0%	higher harmonics of GSM carriers caused by Hitachi PA propagated by new battery. New batterie is comparable to old one.	Verify with B1+		Stefan S.	modify Battery Pack	⊖		Low Market Acceptance Cost Increase; Time Delay	⊖	
8	HW	0%	FL-Foil: Humming EL-Foil itself -> LEDs will be used for keypad illumination.	EL-Foil glued on MMI PCB -> tbv with A1	No EL-Foil!	Roman	LEDs will be used for keypad illumination	⊖		Low Market Acceptance Cost Increase; Time Delay	⊖	
9	HW	0%	EL-Foil: Interference due to High Voltage -> LEDs will be used for keypad illumination.	electrical filter -> tbv. with SLA	No EL-Foil!	Roman	LEDs will be used for keypad illumination	⊖		Low Market Acceptance Cost Increase; Time Delay	⊖	
10	HW	0%	EL-Foil: Life Time of EL-Foil -> specified 3000h THL -> LEDs will be used for keypad illumination	Perform Life Cycle Test	No EL-Foil!	Roman	don't switch on Key-Pad illumination in Car-Kit, or during call LEDs will be used for keypad illumination	⊖		Low Market Acceptance; Higher Return Rate	⊖	
11	HW	0%	Stand-By Time low due to (a) not optimized SW performance (power saver) (b) rel. High quiescence power consumption of SGold2	Assess Stand-by-Time Monitor and Trigger Power Expert Group - done -> Target Batt. Capacity increase to 690 mAh; Estimation of Stand by time from experts was done. Measure stand-by time on B1+ phones (depended on sw)	Measurements done with B2 -> ok	Roman	Relax Requirements	⊖	1/ Okt 05	Low Market Acceptance	⊖	
12	HW	50%	Talk Time low due to (a) small Battery Capacity (b) DAC of Mozart not as sufficient as DAC of SGold2 AFE -> AFE will be employed. (c) Efficiency of PA not perfect	Qualify Voice Band of Sgold2 - done Software optimisations (power saver) --first measurements planned with B1+ Measurement of power consumption of PA	ST2: First measurements of stand by time look promising at B1+ and SVN 76 Measurements done with B2 -> ok	Roman/ Markus/ Stefan Fritze	Relax Requirements	⊖	1/ Okt 05	Low Market Acceptance BOM increase app. 0.50EUR Low market acceptance	⊖	
13	HW	0%	Second Speaker: New concept, not yet verified with SGold2	Qualify Voice Band of Sgold2 - first tests successfully done. Qualification ongoing. Specify Requirements- done.	SGold2 AF qualified	Roman	Usage of external Amplifier	⊖			⊖	
14	HW	0%	SW Support not yet secured: Verification of HW with B1 not secured	B1 software available. Tests still to be done. -> official B1 SW has been delivered	B1 SW available	Roman	Create Test SW within HW dep.	⊖		Time Delay	⊖	
15	MD	40%	Alu Front Cover - new Technology for Siemens, proven at other industries	Expert team at Supplier to find root cause of bonding problem, and stabilise process	Droptest 154cm done: dents at the corners, which cannot be avoided => check again with B1+ and accept! => B1+ droptest done at MD dep.; same status as before => see M1 spec.: PM accepted dents on Front-Cover after droptest Design Cchange with B2.2 -> Drop Performance increased significantly Additionally Safty Measures with B2.3 implemented and tested o.k in drop test. Bonding not stable over process - drop test failed again.	Bischof/ Baur	none	⊖	30/ Apr 06	Low Market Acceptance; Cost Increase; Time Delay	⊖	

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16a	MD	0%	Keypad: Color Matching between Keypad, Front Cover and No ID plate (esp. for non silver color). Intended colour mismatch rejected by CDO.	Sample Test with different suppliers. Best colour matching (Chi Cheng, PVD) = most expensive solution. Samples by every pot. supplier till E07Supplier selection done on 11-Aug. No perfect matting obtained, however, suppliers are progressing.	Color Matching accepted bey CPM/ TPM	Frank S.	Create pre-defined color differences (silver - black); Usage of "pure" colors; Usage of silver-variant only	☹	30/ Sep 05	Low Market Acceptance; Cost Increase; Time Delay	☹
16b	MD	20%	Keypad: Environmental tests fail		DKUIL failed NI and Sweet resistance test -> Cleaning Process at DKUIL will be changed Unlimited release for DKUIL pending Silitec: Environmental test of hard caps passed (3 test reports missing). Drop test pending.	Baur	Additional Clear Coating on top	☹		Increased return rate; Cost Increase; Time Delay	☹
16c	MD	0%	Keypad: 2nd language variant (Silitec) - abrasion of printed artwork	Recheck with improved samples	Siliteck showed etched Artwork for cyrillic -> looks promising. Etched artwork cyrillic, arabic and BPMPF o.k.	Frank S.	Usage of DKUIL cyrillic only	☹	13/ Jan 06	Low Market Acceptance	☹
16d	MD	20%	Keypad: Sensitivity to static load with stainless steel key cap of Silitec.	Migrate to 'hard cap technology' Finish qualification of hard caps (see 16b).		Frank S.	Use You Eal key pad only! Accept increased RR by using soft caps.	☹	30/ Apr 06	Increased return rate 1% Cost Increase;	☹
17	MD	0%	Stability of Battery Cover	Verify with rapid PT parts- done.	B1 parts show sufficient stability.	Frank S.	Increase wall Thickness by 0.2 mm	☹		Low Market Acceptance Cost Increase; Time Delay; Increase Return Rate	☹
18	MD	0%	Aluminum Caps for Keypad new technology -> Artwork etching failed; go for stainless steel.	Verify with Suppliers/ Samples ->	stainless steel will be used for key-caps, Etching ok	Frank S.	Modify ID	☹		Low Market Acceptance Cost Increase; Time Delay; Increase Return Rate	☹
19	MD	0%	Metal Domes attached to EL-Foil -> New Technology -> LEDs will be used instead of foil.	Verify with Samples	No EL-Foil!	Frank S.		☹		Low Market Acceptance Cost Increase; Time Delay; Increase Return Rate	☹
20	MD	0%	Display Lens (glas) glued on Display Module -> New Technology (static load, optical performance)	Verify with Samples ->	IMD-display lens will be assembled into front-cover first; will not be glued to LCD module.	Frank S.	Usage of Plastic Lens	☹		Low Market Acceptance Cost Increase; Time Delay; Increase Return Rate	☹
21	MD	0%	Display Lens (Plastic) glued on Display Module -> New Technology (static load, optical performance)	Verify with Samples ->	IMD-display lens will be assembled into front-cover first; will not be glued to LCD module.	Frank S.	Attach Lens to Front Cover	☹		Low Market Acceptance Cost Increase; Time Delay; Increase Return Rate	☹
22	MD	0%	Wrong Positioning of Display during Assembly due to System Design (pre-fixation on PCB -> adjustment with Front Cover)		No problems found with B2.2	Frank S.	Assembly of display into front cover.	☹	1/ Sep 05	Decreased Yield Rate; Cost Increase; Time Delay;	☹
23	MD	0%	Bumps/ dips at Alu Front Cover after drop test		accepted by PBM	Frank S.	Underfill with material where necessary	☹		Low Market Acceptance Cost Increase; Time Delay; Increase Return Rate	☹
24	MD	0%	EL-foil contacts to MMI-PCB -> new technology at Siemens -> LEDs will be used instead of foil	Verify with Samples	No EL-Foil!	Frank S.	use LEDs with 0.4mm height	☹			☹
25	MD	0%	Aluminum Caps for Keypad -> only 50% yield a artwork-etching-process.->	recheck suppliers information	Stainless steel caps will be employed.	Frank S.	stainless steel keypad has a better yield	☹		Cost Incres; Supply Shortage	☹
26	PCB	0%	Lead Time of Asien PCB Supplier: Problems with shipping and customs with PT PCBs not verified, secured	Escalate to MGM	Happened with B1+ and B2	Thomas/ Sonja	samples will be ordered from both suppliers fir B1	☹	31/ Jan 06	TTM delay	☹
27	PCB	0%	MMI PCB components on side 2: Cut Off of components due to static load during key press	Perform Static Load Test	No components on side 2	Frank S.	Usage of OSP surface No components on side 2 left, as EL foil replaced by LEDs	☹		Low Market Acceptance Cost Increase; Time Delay; Increase Return Rate	☹
28	PTM	0%	Battery connector: Not possible to contact it testing fixture on PCB-Level		proven	Manser	Additional TPs for BATT+ & GND supply.	☹	15/ Okt 05	Decreased Yield Rate	☹
29	PTM	0%	Nano I/O: Not possible to contact in testing fixture on PCB-Level		proven	Manser	None	☹	15/ Okt 05	Decreased Yield Rate	☹
30	PTM	0%	Hirose RF Connector: Bad contact due to particles within Housing		Slightly modified Hirose switch will be used, to avoid dust intrusion	Manser		☹	15/ Okt 05	Decreased Yield Rate	☹
31	PTM	0%	Mounting Display B2B: Bad mounting capability due to missing PCB support (absorb mounting forces)		proven	Manser		☹	15/ Okt 05	Decreased Yield Rate	☹
32	PTM	0%	No ID Concept: Bad positioning of Customer Logo label due to bad mounting tolerance or due to bad placing of mould (small mould and less space for placing due to design reasons. Force to be applied vertically.	verify with B2.2	Automatic Pick and Place Machinery up and running	Manser	Enlarge tolerance and space in mould for placing.	☹		Decreased Yield Rate Low Market Acceptance	☹
33	RF	0%	PA - however existing RF solution		ok	Stefan F.	Relax Requirements	☹	1/ Okt 05	Low Market Acceptance	☹
34	RF	0%	RX Timing of Bright 6E not yet specified. Critica for B1 run -> spec. confirm @25C	Cross-Check with Libra and migrate toward: SGold2	Timing specified and agreed upon	Stefan F.		☹		Time Delay	☹
35	PTM	0%	Problem with SIM-Reader expected for A1 -> B1 Sample run (known by Flamingo). (a) Bad quality of components leads to soldering problems. Has been solved with L1.1 status. (b) Handling difficult (c) Flap may fall apart		Switch to R65 SCR with B2 -> no Problem	Manser/Riedel		☹	15/ Okt 05	Low market acceptance; Increased Return Rate	☹

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36	MD	0%	functionality of battery release mechanism		Tooling Scan report shows problems with locking hooks of Battery Cover. Redesign successful.	Frank S.	None	⊖		Low market acceptance Low market acceptance or increased BoM	⊖	
37	EA	0%	Display spurious in GSM downlink path leading to reduced receiver sensitivity		proven	Stefan S.	Shielding of flex	⊖	1/ Okt 05		⊖	
38	HW	20%	Battery: no second source available		Battery Cell is ok, but problems with new labels. No problem with labels any more	Christian Trautwein		⊖	30/ Apr 06	Increased BoM; Supply Shortage	⊖	
41	LCM	20%	Display: no second source available		Under Coverage of app. 15k in CW6. Problem solved	Andreas Lang	Use Hydra display (same panel)	⊖	30/ Apr 06	Increased BoM; Supply Shortage	⊖	
42	LCM	20%	New keypad technology leading to unforeseen problems		DKUIL failed in CT due to double trigger. MD changed with B2.3, CT adapted. Double trigger problem solved by SW.	Detlev Manser	None	⊖		Supply Shortage	⊖	
43	MD	0%	IO connector too close to front cover - problems with drop test		Drop Test problems with B2 occurred -> Design Modification with B2.3, verified with dummies - o.k.	Frank S.	ad rip on battery-cover for protection	⊖		Increased Return Rate	⊖	
44	HW	20%	Sibley flash availability for mass production	Qualify Sibley 2nd source (STM) -> CR9574	Current technology will be used as 1st/ 2nd source, Sibley as 3rd source. Availability of Sibley not before Q3/06	Roman M.	Stick to current technology Use current technology only.	⊖	30/ Apr 06	Time Delay, Reduced sw feature set Increased BoM	⊖	
45	HW	0%	Internal Stepup: Due to high current peaks in the startup phase of the mobile the shutdown level have to be increased -> in combination with low battery capacity the standby and talk time is reduced	Alternative solutions are being investigated - done: Increased switching threshold not possible (decreased stand-by & talk time). Mozart V Boost+ presently not matching to Polaris time-line. Lockup of RF burst not possible with internal step-up. B1p layout with PF solution will be investigated. Evaluation of this problem by STM: metal fo necessary. From 26-Sep, samples will be available again. -> First samples with bugfix are available and for test some B1+ devices will build up with Twigo 4+	External Step Up must be used	Roman M.	A external stepup converter will be used for the supply of Keypad and Display illumination	⊖		BoM increase app. 0.24 EUR;	⊖	
46	HW	0%	PMU: Twigo 4+ is currently blocked due to technical problems	https://ms.icn.siemens.de/livelink/livelink/Open?31650909	AS SW in Time - migration to Rel. 1 done	Roman M.	Increase quantities of first source (Mozart+)	⊖	1/ Okt 05	No second source available at DS	⊖	
47	SW	0%			see 15, Grilamid screw bosses used	Markus Jäger	Migrate towards Rel. 1	⊖		Time Delay Time Delay; Increased BOM; Increased return rate.	⊖	
48	MD	0%	Glued metal screw bosses will break away			Frank S.	to be evaluated	⊖			⊖	
49	HW	0%	SGold2: Chip cracks in drop tests	Perform Enviromental Test with Cushion -> 6.1.06	Power IC Brakage with B2 discovered, add. Cushion placed for 60k -> afterwards tool change	Roman M. , Frank Schoger	Overmolding over the S GOLD2 silicon / less stiffness of the phone and/or PCB	⊖	6/ Jan 06	Increased return rate; cos impact	⊖	
50	MD	0%	SIM mechanical damage beyond 8N	Verify Tool change -> CW8		Bischof	none	⊖	1/ Okt 05	increased return rate	⊖	
51	PTM	0%	SIM soldering problems due to warpage caused by springs		R65 SCR selected	Frank S.	R 65 SCR: Tolerance analysis to be performed until S25	⊖			⊖	
52	EA	75%	Unclear situation for UC stack up. Decision if separated screwing domes diecast frame or modified diecast frame is used is not taken up to now. To get an final antenna for FCC approval starting in december 2005 b2 antenna have to be grounded have to be evaluated by mechanical available mid of november. FCC approval and D/design, samples for solution have to be provide to EA befor mid of Oct.	Decision which mechanical concept for UC fixing will be used is not done until now with out final decision no antenna data for B2 can be released until 4.10.05. Solution for diecast to EA befor mid of Oct.	New Design with B2.3	Holger Walliser		⊖		TTM delay	⊖	
53	MD	40%	Modified MD shows bad performance with regards to Enviromental Test	Employ new Granulate for. First parts with different granulates (less glass fibres) on their way	Battery Lid: Drop test failed. For FC refer to item 15	Hans-Peter Baur	reliefe Requirements	⊖	30/ Apr 06	Increased Return Rate	⊖	
54	MD	0%	Modified mechanical parts do not match	FMEA held -> Verify with milled parts -> 12.Dec	Speaker Module almos collides with Front Cover latches -> no assembly possible	Frank S.	Remove, shrink Latches from FC	⊖		TTM delay	⊖	
55	MD	0%	Modified FC Aluminium delayed for B2.3	Check on modularity of FC Tool Perform Assembly Test with milled dummies Install 4-Axis at CCC (Rainer N.)		Frank S.	none	⊖	19/ Dez 05	TTM delay	⊖	
56	MD	0%	Modified FC Frame delayed for B2.3	Verify TimeLine with Hosider Check impact on Assembly with milled parts (9-12) Check upon backup solutions	Nolato guaranties delivery in time	Frank S.		⊖	19/ Dez 05	TTM delay	⊖	
57	MD	0%	Modified Speaker Box delayed for B2.3	Perform Pre-Test with modified FC (drilled hole at south) to evaluate impact on Antenna Performance -> 8-Dec	Assembly Test done, assembly not possible	Frank S.	Use B2 Speaker Box for time being, and remove or shrink latches from FC	⊖	16/ Dez 05	TTM delay	⊖	
58	EA	0%	Impact on Antenna Design (not Tuning Area)			Holger Walliser	Accept lower Antenna Performance for time being	⊖	8/ Dez 05	TTM delay	⊖	
59	EA	0%	FCC Approval delayed	Verify TimeLine with Lumberg Clarify Situation/ possible Improvements with regards to hooks		Holger Walliser	Accept lower Antenna Performance for time being	⊖	8/ Dez 05	TTM delay	⊖	
60	MD	0%	Modified BC delayed for B2.3		Time Line ensured, but scan reports show problem with hooks	Frank S.	Use B2 BG -> Impact on Drop Test expected Mili B2 MMI, Cut B2.3 Frame to fit B2 MMI	⊖	16/ Dez 05	Customer Satisfaction	⊖	
61	MD	0%	Modified MMI delayed for B2.3	AT&S Hot Lot (500pcs) ordered		Peter N.		⊖	19/ Dez 05	TTM delay	⊖	

Risks Philippe

ID	Identified by	Owner	Date	Risk Value	Description	Preventive Action	Evaluation	Impact	Probability	Corrective Actions	Status (S2/S25) 2006.03.07		
1	Ralf	CDN	10.11.2005	400	Risk of quality problems and / or delay of DS. Insufficient time between B1 and B2 to evaluate mech parts in depth and do corrections. The same goes for time between B2 and Pilot	Detailed analysis of flow in supply chain, production and testing. Identify focus areas with responsibilities. Possibilities for assembly in AAL vs. KLF for some testing Evaluate options for optimisation of time schedule	After B2 MD pre test 24.03.06	5	80	Improved timeschedule	Achieved for B1 to B2. Project on track.		
2	LCH	CLA	10.11.2005	400	MD time line (general + critical path: new edge key concept)	Detailed analysis of flow in supply chain, production and testing. Identify focus areas with responsibilities. Possibilities for assembly in AAL vs. KLF for some testing Evaluate options for optimisation of time schedule	After B2 MD pre test 24.03.06	5	80		Project on track.		
3	PCS	CLA	16.11.2005	400	Risk of quality and / or time. Mechanical corrective action from B2 run will be tested on pilot series.	Detailed analysis of flow in supply chain, production and testing. Identify focus areas with responsibilities. Possibilities for assembly in AAL vs. KLF for some testing Evaluate options for optimisation of time schedule	After B2 MD pre test 24.03.06	5	80		Project on track.		
4	PCS	CLA	21.11.2005	10	Risk of failure in environmental test for nano I/O (experience from Finch and Polaris)	Use experience from Kestrel (passed) and evaluation results from Finch and Polaris)	Done	1	10		Passed test		
5	RBA	tbc	10.11.2005	10	MMI board has long delivery time (via Leipzig). Risk of delay of B1	Close control of supplier	Done	1	10		B1 deliveries in time.		
6	KIA	KIA	10.11.2005	10	Assume start of TA (BAPT, ?) on B1 (series in Jan 06 FOT mechanics). Then if major changes retest is necessary. Potential time line risk	Only do critical changes	Done	1	10		No changes with impact on TA is done from B1 to B2		
7	LCH	CLA	07.12.2005	10	Risk of dely of sidekeys, due to tactility problems	Partly reuse of minos concept. Design review to take place on Friday 09-12	Done	1	10		Side key tactility okay		
8	BLT		10.11.2005	10	The is no confirmation of DS on 1st May in Primavera plan - delay? The planning as of today show significant deviation between target plan and detailed planning.	Planning must be updated and reviewed	Done	1	10	DS date defined at M1: 29.05.2006 Matched by Primavera planning			
9	BLT		10.11.2005	100	Rea Team has not planned in Primavera (operator test; manual; etc.)	Inform SPM (Claudia) to do it before M1	M1	5	20				
10	LCH	Reiner CLA	10.11.2005	100	High glossy surface is easy to scratch. Used today on Hydra/Neo. Insufficient experience from supplier side.	Use supplier with experience of high Glossy paint. Nolato has been selcted and have good experience	B2	2	50	2006.03.07: SQA and MD to follow up with supplier to improves painting processes. Driver: Andrea Zutz	B1 failed in abbrasion test.		
11	FBA	FBA	10.11.2005	10	Performance on some electrical parameters are close to the limit in Minos and could get on the wrong side of the limit due to new mechanical design.	None - Fixed reuse from Minos	Done	1	10		Performance is okay		
12	FBA	FBA	10.11.2005	10	Support of Sibley memory flash could create unforeseen problems	Support of Tyax & Spansion is kept (Minos)	Done	1	10		Supported in SW and HW. PCB updated for B2 due to missing connection.		
13	ABK	ABK	10.11.2005	20	If FCC TA is started on B1 but there is made a new PCB (label: B2) a complete new FCC approval must be done	Only do critical changes	16.03.06	2	10		Changes done from B1 to B2 but measurements could be done on B1 and then update by paperwork. Evaluation to be done of if it makes most sense to go with B1 or B2 (time vs. effort)		
14	ABK	ABK	10.11.2005	20	If FCC TA is started on B2 then the delivery of samples is time critical	Start on B1	16.03.06	2	10		See ID 13 the above		
15	FBA	FBA	10.11.2005	10	Potential delay of B1 (critical path). Schedule for Vibra is critical for samples and approval. Usual lead time: 40 working days	Order the tooling by now. Done by the 16.11.05 Put pressure on supplier - involve procurement (MGM) Visit supplier	Done	1	10	Close track of suppliers and a delayed time schedule reduce the risk to low. Supplier has confirmed the deliveries. No Problem any more.	B1 finished and the vibrators were available.		

Risks Philippe

ID	Identified by	Owner	Date	Risk Value	Description	Preventive Action	Evaluation	Impact	Probability	Corrective Actions	Status (S2/S25) 2006.03.07
16	FBA	CDN	10.11.2005	10	Support of new accessories that are not tested in the platform (R-IDB / Polaris)	Ensure only use of accessories verified by Polaris	After CR evaluation	1	10	Still open, because the accessories are not agreed with PM.	Support of Music cable is to be clarified. CR to be issued by CPM Carkit linefit is out.
17	ABK	ABK	10.11.2005	10	Camera self interference will not fulfill General Quality Requirements (Internal). Minos does not and improvements made are not expected to be sufficient	None. Changes should not be made in order to reduce risk on schedule	Done	1	10		Solved on B1
18	RBA	LCH	10.11.2005	10	MMI board outline and placement of domes is not available yet. Time critical		Done	1	10		
19	LCH ABK	ABK	10.11.2005	10	ESD protection changed in keypad area (from MMI module to keypad). Risk of incomppliance of TA req.		Done	1	10		Solved on B2
20	LCH	Ralf E. CLA	11.01.2006	60	MMI module can not be qualified before B2 - risk for dust protection	Improved layout compared with Hydra and Hera	B2	3	20		Hajo Langer (Leipzig) confirmed deliveries for B2 on 03.03.06. PO for B2 issued on 06.03.06
21	CLA	CLA	07.03.2006	250	Bad tactility of edge keys. Seen on B1 samples.	Improved for B2. Edge key construction has been changed	After B2 MD pre test 24.03.06	5	50		
22	CLA	CLA	07.03.2006	250	Failure in butter test. Front cover and upper case cracked several places on B1	Improved on B2. Hooks in front cover changed. Radius increased where hooks connect to upper case. Added material around screw buses, radiuses increased and diameter of holes for screws increased.	After B2 MD pre test 24.03.06	5	50		
23	CLA	CLA	07.03.2006	40	MMC tray not locking as easy as intended	Opening in front cover to be increased.	After B2 MD pre test 24.03.06 (tbc)	2	20		
24	PCS	Ralf E.	07.03.2006	200	Risk of damaged/bended springs on microphone and vibrator. Seen on B1 devices. Might not be detected in production in all cases. I.e. risk of market returns.	Assembly instruction must be improved. Driver: Ralf Ehrlich Improved transportation trays. Driver: Andreas Zutz	B2	10	20		Seems that the bending of the springs were not due to transportation but due to the assembly in prototype shop (evaluated 300 lower case in trays)
25	PCS	Reiner CLA	07.03.2006	160	Failure in abrasion test of MMC tray	2006.03.07: SQA and MD to follow up with supplier to improves painting processes. Driver: Andrea Zutz	B2	2	80		R. Römer: New samples to be delivered in KLF CW10
26	MIB	KIA YXI (MAL)	07.03.2006	150	Minos/Hydra was close to the limit of mandatory TA test case due to a timing advance problem. Although improvement was planned for future products this has not been implemented in the SW. Current status is that Philippe fails the test case.	Check if test setup is working properly (KIA) Check what was done on Polaris (KIA) SW improvement must be done (YXI).	07.03.06	3	50		
27	ABK	ABK	07.03.2006	150	Devices with SAR painting done by hand is used for TA SAR measurement. SAR value might deviate for final products.			3	50		
28	ABK	CLA	07.03.2006	500	Tool for SAR painting has a lead time of 10 weeks. Input for correction to the tool given 24.02.06. Risk for DS. Correct SAR painting is important for SAR performance and radiated antenna performance and maybe also ESD performance.	Investigate possibilities for improving the lead time.	10.03.06	10	50		

Hawk PD team Risk List

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Identified by		Owner	Date	Risk Value	Description	Preventive Action	Evaluation (date)		Impact	Probability	Corrective Actions	Status (M1) 2006.04.20	Status (S2/S25) 2006.mm.dd	Status (P5) 2006.mm.dd	Status (DS) 2006.mm.dd
EKJ	EKJ		08.03.2006	80	The window for the flash light in the camera shutter might create light reflections that could interfere with the camera.	Start testing ASAP in order to do improvements in the construction if necessary. Use parts from soft tools	FP (CW14)	2	40		Test performed and first subjective impression is that the pictures taken are of acceptable quality				
EKJ	EKJ		08.03.2006	400	The minimum 25% tactility might not be reached for the integrated keys TPE (soft keys).	Start tactility test with fast prototypes Only limited options for changes - time constraints	FP (CW14)	5	80		Tests will be performed in week 15/16 Subjective feeling on first prototypes is good!				
EKJ	EKJ		08.03.2006	160	Bonding between materials in the 2k molding (TPE and PC-ABS) might be insufficient.	Start testing (incl. sweat test) on fast prototypes in order to do improvements in the construction if necessary	FP (CW14)	8	20		Tests will be performed in week 15/16 Special attention will be included in PSQA planning				
FKO	FKO		08.03.2006	80	TA will be done on B1+ mechanics. The approval can be challenged if there are major differences between B1+ and B2 (on the mechanics)	Only do absolutely necessary changes with impact on TA	B1+ + 1CW	8	10						
ANO			08.03.2006	40	New processes for ASP is not completely "owned" by the departments yet. Cooperation instruction	Follow the ASP Cooperation Instruction	M1	2	20		The cooperation instruction must be followed				
RHE	CDN		08.03.2006	400	Pilot to be started with B2 parts. Risk of corrections afterwards.	Use learnings from Philippe Detailed analysis of flow in supply chain, production and testing. Identify focus areas with responsibilities. Possibilities for assembly in AAL vs. KLF for some testing Evaluate options for optimisation of time schedule	B1+ + 1CW	5	80						
CDN	CDN		08.03.2006	400	Risk of quality problems and / or delay of DS. Insufficient time between B1 and B2 to evaluate mech parts in depth and do corrections. The same goes for time between B2 and Pilot	Use learnings from Philippe Detailed analysis of flow in supply chain, production and testing. Identify focus areas with responsibilities. Possibilities for assembly in AAL vs. KLF for some testing Evaluate options for optimisation of time schedule	B1+ + 1CW	5	80						
REH	CDN		08.03.2006	400	Compressed time line (general + critical path: MD - QM - Production)	Use learnings from Philippe Detailed analysis of flow in supply chain, production and testing. Identify focus areas with responsibilities. Possibilities for assembly in AAL vs. KLF for some testing Evaluate options for optimisation of time schedule	B1+ + 1CW	5	80						
CDN			08.03.2006	400	Risk of quality and / or time. Mechanical corrective action from B2 run will be tested on pilot series.	Use learnings from Philippe Detailed analysis of flow in supply chain, production and testing. Identify focus areas with responsibilities. Possibilities for assembly in AAL vs. KLF for some testing Evaluate options for optimisation of time schedule	B1+ + 1CW	5	80						
YXI	YXI		30.03.2006		If JSR 184 certification is not finalised before 01.06 a newer version is required. Significant additional SW resources might be required.	- Clarify if possible to use Philippe devices - Use B1 (fast prototype) mechanics (available in - Check timing with B1+ devices	FP (CW14)	8	40						
FBA	EKJ		30.03.2006	100	The distribution of the light from the flash light might not be sufficient to reach a proper picture quality in darkness (FBT requirement)	Simulation and synthesis of light guide. Start testing ASAP with parts from soft tools	FP (CW14)	2	50		Simulations are performed and low efficiency has to be expected with the rotational Camera lid. In the team (CPM, TPM) it has been decided to prioritise the rotational function				
PCS	EKJ		30.03.2006	100	Camera lid is a new concept in BenQ Mobile. No preproject has been run	Design FMEA Start testing on fast prototypes in order to do improvements in the construction if necessary	FP (CW14)	2	50		Design FMEA has been performed. Test on prototypes ongoing for optimisation. Decision for implementing spring element in the movement will be decided early in week 17				

Hawk PD team Risk List

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Identified by		Owner	Date	Risk Value	Description	Preventive Action	Evaluation (date)			Impact	Probability	Correctiv Actions	Status (M1) 2006.04.20	Status (S2/S25) 2006.mm.dd	Status (PS) 2006.mm.dd	Status (DS) 2006.mm.dd
PCS	EKJ		30.03.2006	100	Potential lack of resources to measure and analyse MD parts	Get commitment for resources from LM	M1		2	50		Additional ressources allocated part time to the project				

Owner	Date	Risk Value	Description	Action	Evaluation	Impact	Probability	Corrective Actions	
CGT	01.12.2005	10	VF specifications Swift have not planned a VF variant Specifications not known currently	Align w SPM & Thomas Bartel. Received -> changed impact/prob	M1	1	10	Arrange meeting with Swift SWPL and Thomas Bartel	ok
CGT	01.12.2005	150	SW Support transfer from Mch to Aal of the core engine and more modules SW Media performance No ATI chip included Concept and performance need to be proven on Swift	SWPL and Georg Fassler alignment required Alignment with Swift SWPL required	20.03.06 01.03.06	3	50	SWPL & PLT meeting with resp.	ok
CGT	01.12.2005	60	Key operators not confirmed	Align w SPM	M1	3	20	SWPL & PLT meeting with resp.	ok
CGT	01.12.2005	10	Service (test equipment) Will not be available with DS due to the tight schedule Total lead time from B2 samples to service test equipment available: 12 weeks	Reduced I+P BenQ purchase department do have a 6 weeks handling time.	M1	1	10	SWPL & PLT meeting with resp.	ok
HEB	04.12.2005	250	Not expected ready until Sep Dependence on Swift schedule Can influence on the milestones and worst case DS	Align w Swift SWPL	Swift S25 (med feb)	5	50	CCQ clarify with PE CCQ clarify order on basis of B1+	ok
CGT	01.12.2005	180	Dependence on Swift feature set	Align w Swift SWPL	Swift S25 (med feb)	9	20	Verify w. Swift SWPL	ok
CGT	01.12.2005	150	Must strictly follow the Swift feature set Nano I/O connector Breaks of the PCB, by drop test and normal usage	Design according to guideline from platform	Swift S25 (med feb) S2	5	30	Verify w. Swift SWPL	ok
CDU	01.12.2005	200	Camera design Robustness of camera design can be a problem due to 2mm difference to the rear part surface	Plan design review before CW8 to evaluate build-up of mechanical design (TLB, EHO, PCS, FGN, JKR, OHO, CPN . . .)	S2	4	50	Test on B1 run	ok
CDU	01.12.2005	180	RF Bright 6PL Obsidian lead project 19-01-2006: TXVCO PM loop out of lock PCS 1900.	PCB availability of B1 run with new B6PL chip (WS7)	S2	6	30	Test on B1 run	ok
LMM	01.12.2005	80	PVD (physical vapour deposition) coating Limited experience (production, yield rate)	Clarify w. Pre-study in Klf - done Meeting w. Suppliers - done Plan test series before M1, 2*100pcs and evaluate result	B1	8	10	Test on B1 run	ok
CDU	01.12.2005	90	Battery: new battery to be tested and approved - (Physical size as Polaris battery). No confirmation from supplier on deliveries and size. No Second source defined.	Polaris battery is fall back solution. Samsung have confirmed timeschedule. Second source potentials: Sanyo, Sony, LG, Maxell. Second source to be selected. 19-01-2006: Second source defined = LG	M1	3	30	Fall-back solution is painting	ok
TLB	01.12.2005	40	FTA schedule Schedule cannot be confirmed Start testing on B1+	Evaluate B1 run	S2	4	10	Clarify w. Second source companies.	ok
KIA	01.12.2005	140	Requires limited changes to B2			7	20	Test on B1 run	ok

Owner	Date	Risk Value	Description	Action	Evaluation	Impact	Probability	Corrective Actions
Jens-Knapmeier	04.12.2005	80	Definition and availability of FM radio headset- No setup at AD for the FM radio. Not decided if the FM radio will come (expected- CW48)	Amber + VAS (Value added services, Europe)-	M1			
ABK	01.12.2005	80	Risk of noise problems / interference between the GSM part and the FM radio headset BT performance Feeding point for BT antenna is on the other side of the I/O connector BT layout differs to the platform layout (Via's from PMU)	Evaluate B1 run Move feeding point - done Evaluate A1 and B1 run	S2 S2	2	40	Clarify with SPM Test on B1 run
LMM	01.12.2005	80	Speaker module Re-designed module (core as Minos, Hydra) Schedule available	Draft design (CW48) for initial contact with Hosiden 19-01-2006 Confirmed Schedule from Hosiden. /samples available in due time	S2	2	40	Test on B1 run
TLB	01.12.2005	10	Availability of Nano connector Accessories- Samples available in Feb-	Check of Ordering process from stock to Aal- Fall-back solution can be adapter boards for data- cables, where major delays are	M1	1	10	Test on B1 run
Jens-Knapmeier	04.12.2005	60	Single speaker solution ASP (Acoustic shock protection)	Clarify solution with DSP (Driver people) include SWPQA	M1	2	30	Clarify with SPM
CGT	01.12.2005	60	In relation to FM Radio headset MMI-board	-> Resonsibility of AD Currently investigated if production is possible in- Klf	M1	2	30	Meeting w SWPL, Acc, DSP, SWPQA
RMS	04.12.2005	50	Production in Leipzig PSU Mozart Boost+ Obsidian lead project	Consider to make layout compatible to Mozart- (Minos, hydra) -> not possible and not necessary. 19-01-2006: Comp. Qualification is done by KLF- Application test on Obsidian to be done	M1	4	50	Verify w LCM3
TLB	04.12.2005	40	T-flash (micro SD) reader	Clarify w. Product	S2	4	40	Test on A1 board
CDU	01.12.2005	40	Qualification is ongoing Reduced antenna performance in 1800 band due to influence from speaker module ~ 2dB TX	Change gasket on speaker module to conduction version or include a mechanical grounding. 19-01-2006: Course was side keys. These will be shiffted to opposite side of the phone. Expected to be solved.	M1	4	10	Clarify status on lead product - NAME
ABK	03.01.2006	10	Display: Sample plan from Epson not confirmed.	Clarify consequences with MD and Epson	S2	1	10	
TLB	19.01.2006	60	Drawings not confirmed. The guide line for minimum gluing area of 2mm is broken. The mimimum glue distance is 1.1 mm	Design is optimised for glue area.	B1	2	30	as actions
CDU	03.02.2006	150	The Keypad suppliers and Green point has informed upfront that there standart process can not pass the BenQ sweet test.	Test the survirity on real parts Obsidian and test samel orderet before B1 parts	B1	3	50	Optimise process at LPZ Change glue hight
CDU	03.02.2006	60	The build in concept of the LCD is very diffrent than the swift, and is is jugeded that esspecialy the requirement for static load will cause problems	Test large quantaties on B1 of both display suppliers.	B1	2	30	
CDU	03.02.2006	200				5	40	

Owner	Date	Risk Value	Description	Action	Evaluation	Impact	Probability	Corrective Actions
CDU	21.02.2006	250	Splitline on 0.1 mm between front part and base frame may cause stress on the front if the screw domes are too short.	Verify samples from B1 run and adjust screw domes if necessary.	B1	5	50	Adjust screw towers
CDU	21.02.2006	250	Time for MD B1+ test too short, 16 days	Clarify test results from B1 run and estimate necessary test time for B1+ run.	S2	5	50	
CDU	21.02.2006	250	MD submit data for corrections for B2 run before completion of environmental test. (Climatic test and long term test).	Clarify test results from B1 run and estimate necessary test time for B1+ run.	S25	5	50	
CDU	23.02.2006	270	Tool correction not planned for display lense after B1 due to transport of tool	Clarify test results from B1	S2	9	30	
CDU	23.02.2006	40	Tool correction not planned for IMD camera ring after B1+ due to transport of tool	Clarify test results from B1+	S25	2	20	
CDU	03.03.2006	150	Camera ring design 1st priority: Color match 2nd priority: Antracit grey	Check if possible to make acceptable color match. In case not possible, use 2nd priority.	B1	3	50	
Christian	24.04.2006	50	Only very minor modification (5 days) allowed in Upper Case + Battery lid for B2. (Nolato)	Ensure no changes after B1+.	S25	5	10	
Christian	24.04.2006	50	Only very minor or no modification allowed on Window, started earlier than planned B1+ data release. 8 days + weekends for modification reserved. (Nolato)	Ensure no changes after B1+.	S2	5	10	
Christian	24.04.2006	50	Only 5 days reserved for B2 modification allowed on Camera Decoration. (Nolato)	Ensure no changes after B1+.	S2	5	10	
Christian	24.04.2006	0	Camera Decoration tool start 2 weeks earlier than planned B1+ data release.	Not a risk				
Christian	24.04.2006	450	There is no time to evaluate painted Upper case + Battery Lid after B2 modifications before the tools need to be transferred to Nolato Alpha.	Monitor FOTs. Use experience from Philippe.	S25	9	50	
Christian	24.04.2006	450	Volume production will start before BenQ B2 verification is ready based on limited releases. In worst case the Pilot Series may be modified or scrapped. (Nolato).	Start critical environmental test on hand assembled B2 samples.	S25	9	50	
Qle	24.04.2006	0	There are no modifications allowed after B2.					
Edgar	24.04.2006	180	One 4 cavity tool for the uppercase and the same for battery lid. (Nolato)	Possible solution: - Order spare tool (2 cavity) (will also minimize risk #23) / Tony (-> Robert, Andreas)	05.05.2006	9	20	
Andreas	24.04.2006	0	Parts except display lens from Nolato will be delivered during ramp-up, no qualification possible before ramp-up	Possible solution: - "B1+Nolato" run may be scheduled to test first parts in cw27 in Prototyp shop		20		
Andreas	24.04.2006	120	All Housing & Assembly parts (perhaps also keypads) available only 1 week ahead not 2 weeks as requested.	Possible solution: - Regular reporting from suppliers (2 times per week) starting in cw20 until end of ramp-up (depending on situation)	S25	4	30	
Andreas	24.04.2006	0	Color match between camera ring and battery housing	Possible solution: Accept color differences / third color for camera ring		80		
Andreas	24.04.2006	0	PVD process is new for BenQ Mobile / Greenpoint performed poorly during former projects	Possible solutions: - use painted parts - support supplier		30		

Owner	Date	Risk Value	Description	Action	Evaluation	Impact	Probability	Corrective Actions
Josef	24.04.2006	50	Handling of black high glossy parts in factory (high glossy/ scretching)	Possible solution: -FMEA has been performed	S2	5	10	
Arne		0	Influence of PVD double thickness on antenna performance	Use same processes as for Hydra and Philippe				
Tony	24.04.2006	160	Share between PVD and Painting (30/70) may be changed	Possible solution: -Inform Vinzenz (CPM) Only by CR	05.05.2006	2	80	
Christian	24.04.2006	40	Color match between key pad and uppercase	Possible solution: - Use same color system for keypad and uppercase	S25	2	20	
Josef	24.04.2006	10	Repair concept for PVD phones	Possible solution: -Usage of special tool No problem seen on B1 run Possible solution: -Discuss color matching after B1/ decision to be made after B1+		4	10	
Christian	24.04.2006	0	Losing time to discuss color matching (identification/ agreement)	- fallback solution: CPM to visit suppliers and decide			20	
Kay-Uwe	24.04.2006	0	Long lead time components	Ongoing process implemented on 5th April 2006			20	
Andreas	24.04.2006	180	Protection ink process: Peak capacity 96k per week based on equipment -> app. 80k max. display lense	see risk "4 cavity tool"	05-05-2006 and S25	6	30	
Andreas	24.04.2006	0	3 tools (one 1 cavity and two 4 cavity tools) Two different raisins used in the same tool (black and white)	Evaluate possibilty for starting early production see risk "4 cavity tool"			20	
	24.04.2006	0	Lower case and Upper case for Nolato for the two painted versions	see risk "4 cavity tool" Only PVD and Black version is pat of M1-comitment			20	
Trine	24.04.2006	150	Late delivered battery recovery values and measurements done on B1 samples. Risk of need for re-doing measurements on B1+/B2.	Check on B1+ samples	S25	5	30	

Risks Jerry

Risk identification						Risk assessment						Risk handling					
						Total 5.39											
No.	Risk description	Implication on project	Raised by	Status	Identification date	Last change date	Probability	Schedule impact (class)	Cost impact (class)	Exposure	Risk class	Risk handling activity	Trigger	Responsible	Planned date	Planned cost	Status
1	PO team cannot meet the requested timeline from VF	VF would cancel the project if we cannot meet christmas business and NRE have to paid back to VF	PL-T	Active	2006-03-27	2006-03-27	40%	Disastrous	Critical	1.06	Disastrous	Monitor the project timeline closely	big milestone delay more than 2 weeks	Lars Bonde Arjen Broeze Song Xin Juan			Planned
2	MD tooling adjusting take more time than planned since we skipped B1+ run	Have to schedule a special proto run for MD tooling adjustment	MD	Active	2006-03-27	2006-03-27	40%	Critical	Critical	0.52	Critical	Make the first tooling better than normal project	First tooling cannot fulfill the planned quality	Fu Lin Ping Christian P. Nielsen			Planned
3	SW cannot reach the target return rate by DS milestone and S4 milestone	VF cannot accept the SW quality hereby cannot accept Jerry finally	SW	Active	2006-03-27	2006-03-27	40%	Disastrous	Disastrous	1.60	Disastrous	Use Agile SW development method to get SW testing and VF involved much earlier		Yang Yong Qiang Yang Li			Planned
4	Return rate will be more than planned quality	More service cost have to be used for customer care	PL-T	Active	2006-03-27	2006-03-27	10%	Critical	Critical	0.13	Undesired	Get more resource in ST than normal project to find problem in test lab. Get more resource from PD team to get bug fixed before DS and S4	VF cannot accept the quality SPRINT IV and the quality of B1 sample	Ali PPLs			Open
5	Only one supplier for LCD	Mass production have to stop if LCD supplier cannot supply right volum as requested	PL-T	Active	2006-03-27	2006-03-27	10%	Critical	Critical	0.13	Undesired	Take other qualified LCD and re-qualify it in Jerry	Supplier cannot commit the volum for mass production	He Hao Wu Yu Jin Flamming Bach Kristensen			Open
6	Antenna performance cannot full fill VF requirement	Jerry cannot pass VF operator approval	Shan Fu Qi	Active	2006-03-23	2006-03-23	10%	Critical	Critical	0.13	Undesired	BEJ and AAL align the antenna test lab and test result	Antenna test result is not consistent between AAL and BEJ	Shang Fu Qi Arne Bisgaard Kristensen			Planned
7	VF and BenQ cannot make a final agreement on the contract terms	Jerry could be canceled since it is a VF exclusive project	PL-T	Active	2006-03-27	2006-03-27	10%	Disastrous	Disastrous	0.40	Critical	Reestimation the project from both business case and requirement	VF reject to sign the contract	Koh KhengWah			Open
8	VF request more CR after M1 milestone	High possibility for more effort and timeline impact to Jerry	PL-T	Active	2006-03-27	2006-03-27	10%	Critical	Critical	0.13	Undesired	Communicate with VF to skip much effort consuming and timeline impact CRs	VF raised either effort consuming or timeline impact CRs	Koh KhengWah			Planned
9	Handover between AAL and BEJ cannot be handled smoothly	Project DS milestone could be delayed	PL-T	Active	2006-03-27	2006-03-27	40%	Critical	Critical	0.52	Critical	More support is needed from AAL after May/June time frame	B1 proto type production cannot be done on schedule	Arjen Broeze Lars Bonde Song Xin Juan			Planned
10	Cannot make an agreement with VF on patent cost	Cannot delivery devices to VF	Zeng Yun	Active	2006-03-23	2006-03-23	10%	Critical	Critical	0.13	Undesired	Re-negotiate with VF regarding the contract	Contract is signed between VF and BenQ without patent cost covered	Koh KhengWah			
11	ASP concept from 65 generation not accepted by QM	DSP code must be changed in old 65 platform. Risk for DS delay	Lars Bonde	Active	2006-03-28		60%	Critical	Undesired	0.51	Critical	Escalated to top management (Klebsch)	QM blocking M1 milestone	Arjen Broeze Lars Bonde Song Xin Juan			Active
12	Only one supplier for keypad	Mass production have to stop if keypad supplier cannot supply right volum as requested	Lars Bonde	Active	2006-03-28		10%	Critical	Critical	0.13	Undesired	Alternative is to spend tooling money for an additional keypad supplier	SD QM blocking the M1 milestone.	Mariann Svendsen, Christian P. Lars Bonde			
13										0.00							
14										0.00							

CHAMELEON RISK ASSESSMENT

minor:	Targets of the project are slightly endangered, less impact on costs, no impact on time schedule (0...20)						
high:	Targets of the project are endangered, impact on costs, small impact on time schedule (21...60)						
serious:	Targets of the project are highly endangered, remarkable impact on costs and/or time schedule (61...90)						
fatal:	Project may fail, costs completely out of range, schedule may slip up to several weeks (91...100) changed by M changed by M.Krepcke 20.01.05 / R.Kern 31.10.05						
last review Nov. 05	Topic	Impact	Impact	Proba.	Weight = Impact * Proba.	Potential Measures	Comment / Actions
	Description of concern	minor, high, serious, fatal	0...100	0...100%		What to do to avoid an error?	What is done up to now?
Radio (Ralf Dittrich, KLf)							
RF1	RF chipset not fully qualified; final hardware of transceiver IC and PA not available	minor	100	5	500	wait until final hardware is available	measurements are performed in Obsidian in parallel
RF2	Geometry of RF chamber leads to completely new component placement and layout. It is known from Obsidian, that placement of components is critical. Reuse of experience from predevelopment project and Obsidian is limited.	high	100	20	2000	Thorough review of B1 layout. Improve layout or component placement in following layouts.	Careful routing in B1 layout.
RF3	Placement of RF chamber is far away from battery connector. Voltage drop at PA power supply line might be too high.	high	50	20	1000	increase line thickness in following layouts if possible	Careful routing in B1 layout.
RF4	Placement of RF chamber is far away from antenna pad. This might lead to degraded RX sensitivity and mismatch between PA and antenna.	high	50	20	1000	optimize impedance of antenna line in following layouts	Careful routing in B1 layout.
RF5	Placement of FM radio in upper part of the mobile leads to a long antenna connection which has to be routed through the whole PCB. Degradation in FM receiver sensitivity might be the result.	minor	20	30	600	optimize routing of antenna line in following layouts.	Careful routing in B1 layout.
					0		
Baseband (Gerd Batke, KLf)							
BB1	MicroSD card reader: Malfunction due to high capacitive load on data lines.	minor (high?)	30	20	600	Measures (see right column) to be checked with assembled B1 phones. Worst case scenario: MicroSD reader has to be removed from Chameleon.	First measures have been taken in B1 layout (removed EMIF, replaced by resistors).
BB2	FM radio: GSM noise picked up by audio lines due to "disadvantageous" position of FM radio shielding chamber. Routing of audio lines from radio to BB chamber is critical.	high	100	20	2000	Layout review B1.	
BB3	SMT Microphone: New technology (SMT mic necessary in Chameleon for height and dia. reasons). Failure rates in production unknown up to now.	minor	30	10	300	Altogether three sources are under investigation, to lower the potential risk to encounter problems.	Tests with Swan-A1 showed no failure with 42 PCBs equipped with Hosiden-ECM, tests with other suppliers (Bujeon, BSE) are ongoing.
					0		
					0		
					0		
EMC / Antenna (Abbas Alpaslan, KLF)							
EA1	No Mockups available for M0 measurements >> e.g. operator requirements for antenna requirements may not be fulfilled	fatal	100	20	2000	Design in proven solutions as good as possible	1st mock up measurement started on 05.12.05
EA2	Not-shielded camera lead to reduced RX sensitivity during viewfinder mode	serious	80	20	1600	Mock ups have to be measured and severance has to be investigated >> Shielding concept to be evaluated (tbd)	
Layout & Production Data (Kai Jäschke, KLf)							
LPD1	Soldering on FPC for Components	serious			0		
Mechanical Design (Andreas Hülsmann, KLf)							
MD1	ClipIt cover may not fit properly (too tight/too loose) and will not be accepted by BenQ quality assurance	high	50	20	1000	Has to be investigated during B1/B1+/B2	

last review	Topic	Impact	Impact	Proba.	Weight = Impact *	Potential Measures	Comment / Actions
MD2	Design may not fit into the Q3/06 market (Portfolio dimension goal: 85x43x21)	serious	70	20	1400	1st design/mech stack up already stopped (too thick, too width), new stack implemented	>> new dimensions: 88,6 x 47,6 x 19,6(18,9@border) mm reached >> Design is accepted by CPM
MD3	No Design Acceptance Test before M0 due to late availability of design office and general design decision by CPM	fatal	100	20	2000	Decision by CPM to declare M0 without DAT	
MD4	Usage of Hinch SIM reader (Polaris) leads to problems during drop tests	high	50	40	2000	65-generation SIM reader (as ARIES) will be used	
MD5	Distance between display & display lense too low >> static load requirements (>=200N) from QM will not be fulfilled	high	50	50	2500	>> Implement cushion >> Align QM requirements versus design	

Software (Hans-Henrik Skovgaard, AAL)

See also link: \\10.97.109.73\vol1\DATEN\GRUPPEN\KLF_ALL\ENTWPROJ\X95_Chameleon\PD-TEAM07_SW04_ProjectManagement\25_RiskMgmtPlan\Chameleon_SRMP_20060228_v1.xls

	Dependent on sw deliveries from Obsidian. Obsidian are going to implement the FM radio.	serious	100	40		Follow Obsidian closely.	
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Systemtest 1 (Pascal Revenus, KLF)

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Systemtest 2 (Roland Göhringer, KLF)

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LCM4 (Achim Körber, KLF)

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LCM1 (Ralf Heesch, KLF)

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SD-QM PRO (Markus Teews, KLF)

	Supplier KHVatec doesn't fulfill technical availability and quality	serious	90	90	8100	New supplier selection for Mg + Slider Parts	
	Feasibility Commitment not available for Silitech + Dkuil (Keypads)	minor	20	20	400	Commitment is being requested	
	Feasibility Commitment not available for Career + MFlex (Flex)	minor	20	20	400	Commitment is being requested	
	Keypad Bezel Illumination has been accepted by CPM (Intensity + Colour)	minor	20	20	400	No colored Parts for the Bezels	Acceptance by CPM during B1

CCQ QM (Zlatko Kirin, KLF) Quality Management, HW-PQA

	No direct illumination of the keys (no transillumination of the symbols). Only a defined gap around the keys will be illuminated. Worst case: The customers will have to guess where the right key is (starting time).	serious	80	35	2800	Switch to second solution. Standard keypad, ease to release, but boring design.	
	SD card could be pushed between the card holder and housing. This could lead to different damages but the card couldn't be removed anymore.	serious	90	50	4500	High risk. But due to the fact, that the SD card reader can be removed from the phone concept if that problem would really occur (after the usability test with B1 samples) this is NO BLOCKIN POINT FOR M1.	
	Removing cycles for changeable covers will not reach the required 500 cycles because of the screwing concept. Usually the screw bosses can "only" be used up to 6 times. If a user changes the upper case more than 6 times, the screw bosses would be damaged.	High	40	80	3200	No measure available	
	Camera/camera flex without shielding. Reduction of the antenna performance expected.	high	60	50	3000	no measure available / shielding will increase thickness	test and analyse during B1

CCQ QM (Reinhard Peters, KLF) Quality Management, SW-PQA

QM.1	For ST it is decided not to run a full system test for milestones S25 and S3. So there is a risk to introduce new undiscovered failures due to side effects during bugfixing and introducing new features.	serious	80	25	2000	Make a clear test strategy and track the changes to the software after the last full test run and define test cases to test these changes.	
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CCQ GRM (Volker Jessusek, KLF) Service

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last review	Topic	Impact	Impact	Proba.	Weight = Impact *	Potential Measures	Comment / Actions
	SP (Thomas Görig, KLF) Strategic Procurement						
	AD (Thorsten Lange, MchG) Accessory Devices						

	colour grey > status done minor risk expected
	colour withe > risk evaluation ongoing

Risks Diamond

low :	Targets of the project are slightly endangered, less impact on costs, less impact on time schedule	X95 DIAMOND RISK ASSESSMENT 19.04.2006 - update for M0 on 21.04.2006						
medium	Targets of the project are endangered, remarkable impact on costs and/or time schedule							
high :	Project may fail, costs completely out of range, schedule may slip up heavily							
issue No.	risk	Impact	risk class	Probability 0%-100%	measure What to do to avoid an error ?	responsible Owner	target date for risk reduction	outcome What is done up to now ?
PM								
see risk list REA-Team								
RF (Michael Niederholz 4038)								
1	Smarti PM does not pass FTA	no type approval possible	fatal	5%	contract with Infineon, that RF solution must fulfill the GSM spezifikation, tests with A1, B1 and B1+ devices, solution must be available with B1+ devices	Niederholz	first A1 PCB/device	
2	No approvals due to display / camera RF interference	no type approval possible	fatal	5%	Tests with A1, B1 and B1+ devices. Solution must be available with B1+ devices.	Niederholz	first A1 PCB/device	
BB (Reiner Wiechert 4018)								
1	camera generates interference	lower Bluetooth sensitivity	high	10%	Tests with B1 and B1+ devices. Solution must be available with B1+ devices.	Wiechert	B1 device	
2	camera shows noise in picture	customer dissatisfaction	low	10%	Tests with B1 and B1+ devices. Solution must be available with B1+ devices.	Wiechert	B1 device	
EA (Markus Kückelheim 4118)								
1	unsatisfying position of speaker	bad antenna performance in closed mode	medium	40%	align with MD and acoustics	Kückelheim	S0	
2	antenna cable => mechanical performance / solder connection breaks	no antenna performance	fatal	20%	further Q tests => confirm mech. Fixation	Kückelheim	S0	
3	reliability of new supplier Bujon	bad antenna performance	medium	10%	samples to be tested	Kückelheim	M1	
4	no solid electrical ground-contact slider <=> module	EMC resistance can become worse	fatal	40%	reliability of mechanical contacts	Kückelheim	FMEA	
5	PC-ABS not ESD conform	Front end defect due to antenna concept (monopole)	fatal	5%	check PC-ABS on dielectric strength	Kückelheim	S0	
6	new display type	high self interference level	medium	30%	additional position for SMD components forseen	Kückelheim	So	
LPD (Heinz Rauch 4084)								
no issues for M0								
MD (Nelson Gonçalves Pimentel 8625)								
1	rattling 'wackeln' between slider and base-part	customer dissatisfaction	medium	30%	optimization, tolerance compensation; 2nd solution under evaluation	Pimentel	S0	
2	damper mechanism (end position damper)	customer dissatisfaction (sound, pulse)	medium	25%	test with milling-parts; fallback-solution to be evaluated	Pimentel	S0	
3	keypad sheet-metal has a tactility range	customer dissatisfaction; non-functional keys	high	20%	Kestrellösung als Rückfallebene Kraftbereich definieren durch PM / schnellstmöglich Muster von Lieferanten anfordern	Pimentel	S0	
4	stability of Metal-Base Housing in open position (< 180 N)	customer dissatisfaction; non-closeable device	medium	10%	increase material thickness -> increase thickness of design	Pimentel	S0	
5	coax-wire damaged	bad antenna performance	high	20%	guiding for coax	Pimentel	CW18	
6	ZIF-Connector	Bad mounting / flap not closed	high	20%	Check Hirose ZIF-Connector with spring flap	Pimentel	S0	
7	Releasekey	accidentally open through releasekey probably (embossed key in design implemented)	high		- frame around key to protect button - devide button in two areas (moveable and fixed area)	Pimentel / Betting	S0	
8	Swelling (blocking through swelling of battery)	No demounting of battery cover possible	high		maximum swelling not implemente yet (0.4 instead of 0.6mm)	Kirin / Betting	CW16	
9	PCB main	Fixation of both pcb's Sheare of B2B connector through relative movement of both pcb's	high	20%	strong fixation between pcb's through force closure (FEM-Simulation)	Pimentel	50% data	
10	Soldering process	stability deformation of soldering process due to pcb thickenss (0.6mm thickness)	high		- 0.6mm pcb with new BT placement - avoid Spiegelnutzen (cost impact 2€/ device) - increase pcb thickenss from 0.6 to 0.9mm - Manufacturing extern (buy part?)	Pimentel	CW18	
11	Springsystem	Durabilitytest	high	new technology	Choose of right material	Pimentel		
12	Impression	Through non-conductive vacuum metallization (chrome effekt) colour matching with other parts critical	high	new technology, see experience in Obsidian	CPM should define boundary sample	Clemens		
all other points handled in System-FMEA (to find under X95 -> PD-Team -> MD -> FMEA or click:		PD-Team\020 MD - Mechanical Design\FMEA\Diamond system FMEA 190406.xls						
LCM 3 (Carsten Schilling 4819)								
1	BT-Device will be placed on daughter PCB board.	BT can't be tested on usual way. New testing solution need to be defined and evaluated.	high	10%	Test concept has to be define	Schilling	CW19	
2	Main PCB very small (35x39mm). Component dencity very high.	Because of this fact is questionable if there is sufficiend area for all needed testpoints. Will be defined and agreed in Testtechnologie Workshop.	high	10%	Test concept has to be define	Schilling	CW20	
4	very complex and difficult assembly concept	global concept available, but not economical	med	20%	assembly concept has to be define	Schilling	S0	
5	new SW Plattform (APOXY) factory interface (lib) is not confirmed		high		meetings between SW and PT are planed (responsible is Tomas Pospischil)	Schilling	S0	
6	APOXI development during product project	see Qualcom	high					
VAS (Thorsten Lange MchG 2741)								
1	Headset development timeline	not available for DS	medium	10%	drive decision for headset contract	Lange	S0	
2	SW requirements from VAS not yet confirmed by SW	accessories not supported	high	20%	Jens Knapmeyer: to be followed up until M0 / tomorrow			
ST (Sylvia Schellberg-Geiger 4089)								
ST1_1	BenQ ST process needs to be adapted to agile SW implementation process	jeopardize incremental SW impler	serious	50	Possible to decrease the priority of endangered features. But not possible for features which are in the minimum usable subset.	Schellberg	S0	
ST1_2	Bug tracking via different sites, companies & systems leads to a slow bug prioritization & fixing process.	responsible party might be difficult	high	40	How are IFX/Comneon, Teleca, Aplix included ? How can we reach a quick communication and distribution between the different participants.	Schellberg	S0	Daily meeting to prioritize the errors must be setup. Daily FTT meeting must be done BenQ
ST1_3	Due to agile development process full tests are only planned for new features in an iteration. Previously delivered features will be only tested in regression intensity.	will not be found because of regre	high	40	Definition of regression test cases which cover a wide functionality area of the tested feature.	Schellberg	S0	
ST1_4	Information flow is more complicated due to the number of 3rd party suppliers.	Loss of information is more likely.	high	40	Defintion of E-Mail distribution lists, folder structures, responsibilities who as to inform whom	Schellberg	S0	
ST1_5	Features have been shifted from one site to another within ST organisation (for example java certification shifted from ULM to WRO).	e about this feature at the new site	high	40	Additional trainings with the former sites. Support by 3rd party suppliers.	Schellberg	S0	
ST1_6	Reaction time on bug fixes will be extended, because of complex SW supplier structure.	in sw debugging process. Target fo	serious	30	Release cycles have to be shorter than 3 weeks during the last project phase. Daily builds and fixes should	Schellberg	S0	Clarification within integration group is needed.

Risks Diamond

ST1_7	SW tests can only be done on PCB/Wing Board level for the 1st iterations. DIAMOND can only be tested on PCB and A1 SWAN wingboard.	will be found later when test depth	high	50	Order high number of A1 Wing Boards (add. cost 70k EURO)	Schellberg	S0	Check test strategy - Peter Hennig
ST1_8	Feature list is still under heavy modification due to open points and clarifications.	to prepare test plans and common	serious	30	Clarifications have to be finished to come to final state and final state of FL has to be delivered to ST.	Schellberg	S0	
ST1_9	Contracts are not fixed until now. Open pending problems like Delta Description / Release notes.	ual negotiations can slow down da	serious	40		Schellberg	S0	
ST1_10	Sprint planning list is not detailed enough to define precisely the acceptance and system test cases for the different sprints.	h and dependency to detailed cont	high	50	The scrum teams have to define in detail what should be delivered within the next sprint derived from the sprint backlog	Schellberg	S0	
ST1_11	All ST SW Testcases have to be delivered to th 3rd party suppliers in an early stage.	the test cases are only prepared fo	high	60	Clear definition of acceptance tests and test strategy (components tests, feature test, integration tests, use cases)	Schellberg	S0	
ST1_12	Process of MMI modifications and documentation during development is not clear.		high	60	Definition how MMI changes should be handled and documented. When starts CR process?	Schellberg	S0	
ST1_13	Due to APOXI platform new interfaces in comparison to native platform are needed (for example environment for java certification or MTPP test automation).	ts are not clearly defined and avail	high	40	Tracking of progress of CRs in CCB and ST requirements.	Schellberg	S0	Definition of the ST1 requirements and communicated to 3rd party suppliers.
ST1_14	Dongle usage is mandatory for Comneon tooling.	down test process if not enough d	high	30	Comneon should provide tooling which can work without dongles. In the meantime additional dongles might be necessary.	Schellberg	S0	
ST1_15	GCF certification of IMPS feature not clarified until now.	an result in additional costs and effc	high	40	Continuous check of the IMPS test strategy defined by the GCF.	Schellberg	S0	
ST2_1	Rel4 Protocol stack too buggy / NO EGPRS-Rel4 phone with Comneon PS on the market so far		serious	20	Check Rel4 pre-IOT/GCF test results from Comneon to adress potential problems asap >> SwanApoxi A1 Layout under evaluation	Abratis	S0	Comneon IOT Reports will be available end 06.06
ST2_2	Reaction time on bug fixes will be extended, because of complex SW supplier structure.	in sw debugging process. Target fo	serious	30	Requirement "2 days for critical and 5 days for major bugs" are defined in BenQ / Comneon contract, already mutually agreed during workshop	Abratis	S0	Wait for agreement of contract!
ST2_3	Too many HW changes from B1+ to B2	All changes must be described.	serious	20	Pay attention to RF conformity during first testruns to detect HW problems.	Abratis	S0	HW Systemtest-runs has started since cw07
ST2_4	Continuous conformity to GCF versions is not fixed in contract between BenQ and Comneon/IFX.	approval feasibility is highly endan	serious	40	Continuous conformity to GCF versions has to be fixed in contract between BenQ and Comneon/IFX --> included in contract by BenQ now but no commitment from Comneon so far - neither verbally nor in written form	Abratis	S0	Wait for agreement of contract!
ST2_5	The process of delivery of SW delta description to BenQ for the SCODA data base is not fixed.	rocess will endanger type approval	serious	20	A BenQ template for release notes is available and has to be confirmed by Comneon, PSE and all third parties. Actually only BT is still open; all other parts mutually agreed.	Abratis	S0	Wait for agreement of contract!
ST2_6	Existing BenQ test automation for protocol stack tests can not be used for APOXI. An APOXI specific environment to execute protocol stack tests is required.	will increase effort for type approval	serious	40	Test automation is actual in verification. First results are expected in CW 2006-7: actually switch on and sending of AT-commands is o.k., switching-off is only possible by hardly disconnecting the power supply which results in several testcases fail	Abratis	S0	Comneon agreed to support BenQ in this topic.
ST2_7	Bugfixing during cost-intensive IOT sessions has to be done in time for an effective retest.	until "New SW available" must be d	high	70	A competent and qualified single entry point for IOT bug reports has to be defined (e.g. in the BenQ/Comneon/IFX contract). See also ST2_3	Abratis	S0	Ralph Dümmler (Comneon) offered to support the IOT bugfixing (agreement on working level only).
ST2_8	It's not allowed to provide IOT reports from Comneon to our customers (operator)		minor	50	Ask comneon to get this permission. Will be decided by Comneon case by case on operator request.	Abratis	S0	
ST2_9	Release cycles have to be shorter than 3 weeks during the last project phase		high	70	Define this requirement in BenQ / PSE contract. Requirement <= one week. Official SW version planned to be released on a weekly basis	Abratis	S0	Wait for agreement of contract!
ST2_10	Trace tools (mobile analyser) do not provide the comfort of WinResi tool	> bug localization more complicate	high	100	No way to avoid this problem. We have to use the comneon tool. Comneon does not accept our request to improve their trace tool.	Abratis	S0	Request done and declined by Comneon
ST2_11	Actually it is not possible to trace and to transfer data in parallel via one USB connection	ssential test feature missing for IO	serious	30	In clarification with Comneon, Karl Boehlke - according to his statement this is already running at their site with the MPE boards	Abratis	S0	
SW (Tomas Pospischil 8439)								
1	New CM Setup and CM tooling might have impact on team speed	Increase effort; may cause delays	low	10%	Setup system as soon as possible	Dirk Lerch		
2	New, only partially defined process framework. Unclear workflow might slow down the team	Increase effort by not well defined workflow & big team	low	10%	Define process as the project need it. Clarify open issues on short notice.	Uwe Schmitz		
3	First usage of APOXI platform within BenQ. No deep system knowledge available	Delay because of increased effort for architectural and implementation tasks	medium	40%	Training & Education of all participants before the project starts.	Line Management		
4	Project taken over from PSE, which was in the driver role. Current state unclear		medium	60%	Embedd PSE experts in BenQ team; use already existing PSE assets to steer the project	Tim Hagemann		
5	Project staffing not finished yet. Some key resources bound in ongoing projects	Delays because team velocity lower than expected	medium	10%	Finalize project staffing asap	Tim Hagemann		
6	Supplier contracts still in negotiation	Delay because of not processed SW deliveries,...	high	40%	Finalize contracts asap	Patric Houben		
7	Requirements still under negotiation	Delays because implementation cannot start	high	60%	Freeze feature list; new FL approach	Tim Hagemann		
more detailed risks can be found: Gemstone Apoxi Risk List in Livelink								
QM SW (Reinhard Peters 4145)								
1	Exit handling concept may be changed, efforts for adaptations are underestimated, no valuable input for QM is available	MTBF can not be estimated	medium	80%	Check together with SMS on Exit group the requirements	Peters	S0	
2	Requirements for MobiCon not finalized	No initialisation of variants possible anymore	High	40%	Check togeter CustTools group	Peters	S0	
3	Customers will find bugs after acceptance by BenQ (e.g. during operator approval).	This may lead to additional costs.	High		Check maintenance release in contracts with 3rd parties	Peters	S0	
4	Feature list and gap are combined but not yet reviewed	May be user concepts are not fulfilled.	medium		Arrange review with UI spec team	Peters	S0	
5	Modifications in interfaces and lower layers will lead to changes in other parts in the SW which are handled by different suppliers	responsibility for bug-fixing unclear	High		Architecture-Control-Board will be established and detailed design specs needed to describe the interfaces	Peters	S0	
QM SQA (Kay-Uwe Clemens 5047)								
1	Bending the coax-cable changes the impedance.	antenna performance changes between open and closed position	low	5%	follow supplier-requests concerning bending radius etc.	Clemens	S0	

Risks Kestrel

Risk Assessment (Rel 1.3) - S3 Version (14.02.2005)													S2 Status		S25 Status	
Group	No.	Risk	Root Cause / Consequence	Impact	Probability	Measure	Owner	Date	Result							
MD	12	Cracking magnesium housings	brittle material	3	2	add radius, B2: 0.4 mm more wall thickness. B2: Drop test 1.2m passed / 1.5 m failed	Klett		Environmental test team							
MD	13	Quality problems after drop tests and static load	extreme miniaturization	2	1	add security margins, thicker walls, increased thickness. B2: BLC still breaks sometimes at drop test 1.2m	Klett		Environmental test team							
MD	14	Dust under display lens for customized variants	Quality problems	2	1	invest into clean config center, protect display Ziolkowski module with foil during transportation			internal							
MD	15	New Material: reinforce PA change from 30%GF (IXEF 1002) to65% GF (IXEF 2060)	brittle material, difficulties by painting, USWelding, hot stamping	3	2	B2: US welding connection OK. Heat stake connection between BUC and Base Upper Cap still break sometimes at drop test 1.2m. BLC screw latches break	Klett		Environmental test team							
MD	19	3-Layer FPC with 80pins connector	cracking after cycle tests cracking while testing or assembly	3	2	optimize length and geometry of FPC. Ichia B2 and version 2.5 from Caneer and MFLEX OK.	Klett		Environmental test team							
MD	21	optical defects on Mg-Parts, maybe EMV-problems	corrosion	1	3	improve chromation/coating of raw parts	Klett									
MD	22	Cracking of USW between FlipUpper/Case and FlipLower/Cap during drop test	too small US-rib, too soft material	3	2	Material changed to IXEF 2060.B2: US welding connection OK	Klett									
MD	23	dust under MDF of Topkey-Assembly	too small gluing area in cause of additional LEDs	2	2	increase Topkeys-FPC and gluing area up to B2. OK at 1 supplier, 2nd source still problem										
EA	28	No EA measurements done with final mechanical status	Influence on EMI and antenna performance	3	1	mechanical changes	Huber		internal							
QM HW	31	Increased Return Rate	Environmental tests not finally finished due to PS/ DS scenario	3	3	none	Sutther		as usual							
QM HW	32	Increased Return Rate	General Quality Requirements dropped not fulfilled. Cracks in EL-Foil	3	3	mechanical adaptations in B1+ B2(increased thickness) Crack-out in EL-Foil	Sutther		Environmental test team							
ST	37	The 3GPP mandatory features 1. Secondary CPICH 2. Compressed Mode by Puncturing 3. Closed Loop TX Diversity (mode 2) 4. Site Selection Diversity TX (SSDT) 5. Hierarchical Cell Structures (HCS) are not fully supported by OCT platform	Item 1) and 5): Inherent risk that operator might want this feature during life time of Siemens products. Siemens could be forced to withdraw Certified Status. Clear core spec violation. Item 2), 3) and 4): Feature was removed in Rel5 because nobody was / is interested in this feature. Feature still part of R99 and Rel4. Probability is low that GCF insists on this feature for Rel99 and Rel4 terminals.	2	3	no measures	Sadler		internal							
ST	41	Documentation of Kestrel for approvals For TA SW description and SW Datasdescription is required. This is currently working for W5.	Approvals can not be reached within schedule and planned efforts. Increased effort and budget for ensuring ongoing compliance	2	1	Tracking Wolf4/5 status Ongoing contact to System Test OCT	Sadler		?							
SW	48	Dependency on Wolf4/wolf5 14.02.2006 the last release from W5 was integrated in CW 51; => risk entered		3	3		Langefeld		see 3							
SW	51	Reduced FPS on display due to e.g. 8bit bus		2	2		Langefeld/Richt		Info							
ST	53	Operator Approvals maybe not be finished for DS	Between AS and DS are only 7 weeks (incl. Christmas) planned. Normally 10 weeks are needed.	2	3	Time schedule of Kestrel needs to be discussed with PLT, GPM, SW and ST e.g. AS needs to be moved to the date of S3 SW availability (CW 50)	Wiedmann		internal							
SW	66	Core integration team is not staffed for 3G SW platform 01.08.2005 two additional experience persons from L1 were added to the team; discussion to add further persons to application area is ongoing 14.02.2006 established CIT K3 is moving to unexperience OCT CIT in Mch	delay during SW stabilization phase	3	3	Get support from native SW, proposals distributed to SW line management	Liemen		HW-SW Coordination team							
SW	68	first time that component developing was started at 3G platform. Nearly all component developers are unexperience with embedded systems. 14.02.2006 established a team in SD also for know how transfer and solving critical bugs	no reliable planning available	3	3	added one experience PLC to Dev.2 to control active component developing	Liemen		ongoing							
SW	69	out of the platform is still no PC-Simu available	developing direct on target cause additional effort => delay	3	3	PC-Simu has to be established for Kestrel	Liemen		a team was set up to prepare a PC-Simu for Kestrel => ongoing 14.02.2006 PC-Simu now available but still not really used for development							
SW	70	additional huge feature should be insert into SW at a late integration date of the project (JSR205; LiveCast; DRM watchdog; movie ringer tones) 14.02.2006 still a huge amount of CR arrived during the late phase of the project; still some requirements were not implemented in W5 and were committed to the operator for Kestrel	this will reduce the stability of the SW; high risk to the DS date	3	3	add such features in a additional SW release	Liemen									
MD	81	Base Lower Case screw latches break, see also point 15	Brittle material IXEF 2060 and too much clearance in the hinge system	3	2	1. Recurse the clearance in the hinge system. 2. Increase the height of 2 stopper ribs in BUC and decrease the internal diameter of the sliding surface in the FLC. 3. Test BLC with IXEF 1002 (30%). Change if warpage in assembled situation is acceptable.										
MD	82	Base Lower Case breaks in southern corners at drop test 1.2m.	Brittle material and insufficient amount of material due to slim line concept	2	2	None										
SW	83	at the moment it is planned to sent the SW in 35 variants to the operators; here is a high risk of losing the focus of the real critical issues; it is expected that a lot of feedback from the operators lead to no planned additional effort to SW development		1	1	* discuss with PM to focus an TOP 5 operators * filter incoming feedback from Operators from ST	Liemen	14.02.2006								

Risks Onyx

Onyx RISK ASSESSMENT (M0-Update)																	
minor		Targets of the project are slightly endangered, less impact on costs, no impact on time schedule						Remaining RISK, after potential measures has been efficiently established!				Remaining RISK, after potential measures has been efficiently established!				Remaining RISK, after potential measures has been efficiently established!	
high		Targets of the project are endangered, impact on costs, small impact on time schedule															
serious		Targets of the project are highly endangered, remarkable impact on costs and/or time schedule															
fatal		Project may fail, costs completely out of range, schedule may slip up to several weeks															

[illegible]

Software
(Gerhard Seibold: +49 89 722 50092) last update 13.03.06

[illegible]

SystemTest (Holger Abratis 4078, Mirko Virkus 8853)

[illegible]

SCM-QM (Markus Tews) last update 17.03.06

Feasibility Commitment or FSR for supplier not available	minor	20%	feasibility is being requested		Feasibility OK	minor	20%
It is possible that the basis of the above items will be visible on the Front cover	minor	20%	accepted by CPM requested	acceptance after B1 by CPM	accepted after B1 by CPM	minor	20%
It is possible that there will be visits prior or unannounced on the Front cover	minor	20%	accepted by CPM requested	acceptance after B1 by CPM	accepted after B1 by CPM	minor	20%
Display controller L400000 quantities are not available	major	80%	second source	no second source (see below)	using second sources	major	80%
Unclear Assembly concept for Keyboard flex (GM C6)	minor	20%	To clarify by REA Team	clarified	clarified	minor	20%
Single source concept for critical components was decided by FYM (Flex supplier, MOF, FSR for, Main PCB, Display Controller)	serious	50%	second source	no second source	using second sources	serious	50%
Ramp LRP quantities for housing=assembly Components not fulfilled. Ramp Up Plan V 3.1 / 23.02.02 not fulfilled under 1400000. Delivery until 1 calendar day before Pilot.	serious	50%	supplier has to deliver earlier	if possible	supplier has to deliver earlier	serious	50%

Bar	Red	Green	Yellow
1	50%	0%	50%
2	50%	25%	25%
3	50%	0%	50%
4	0%	100%	0%